



ITW

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST-CLASS MAIL IN AN ENVELOPE ADDRESSED TO: COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, ON December 8, 2005.

Depositor: John A. Jordan

John A. Jordan 12/8/05  
(Signature and Date)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of : December 8, 2005  
John H. Magerlein, et al. : Examiner: N/A  
Confirmation No.: 2811  
Serial No.: 10/771,817 : Art Unit: 3965  
Filed: June 16, 2004 : IBM Corporation  
Intellectual Property Law  
Dept. 1Q0A/040-3, 1701 North Street  
Endicott, New York 13760  
Title: METHOD OF MANUFACTURE OF  
SILICON BASED PACKAGE AND  
DEVICES MANUFACTURED  
THEREBY :

**STATUS LETTER**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The status of the above-identified application, Serial No. 10/771,817 filed on June 16, 2004, is requested.

Respectfully submitted,

John H. Magerlein, et al.

By:

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WHS/JAJ

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